

# MATERIAL DECLARATION SHEET



Material Number	PTVS15-076C-SH			
Product Line	Semiconductor products			
Compliance Date	September 1 <sup>st</sup> 2013			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.836600	Bisphenol Epoxy Resin	1675-54-3	40.00	5.40	13.49
				Epoxy Resin	25085-99-8	20.00	2.70	
				Crystalline Silica	14464-46-1	23.00	3.10	
				Brominated Epoxy Resin	40039-93-8	12.00	1.62	
				Iron Oxide	51274-00-1	2.00	0.27	
				Titanium Oxide	13463-67-7	3.00	0.40	
2	Electrodes	Copper	3.525566	Copper	7440-50-8	99.10	56.36	56.87
				Silver	7440-22-4	0.40	0.23	
				Other	-	0.50	0.28	
3	Terminations	Copper	1.149108	Copper	7440-50-8	99.50	18.44	18.54
				Other	-	0.50	0.09	
4	Termination Finish	Silver	0.015494	Silver	7440-22-4	100.00	0.25	0.25
5	Chip	Silicon Die	0.319216	Silicon	7440-21-3	85.34	4.39	5.15
				Aluminium	7429-90-5	5.13	0.26	
				Nickel	7440-02-0	9.09	0.47	
				Gold	7440-57-5	0.44	0.02	
6	Die Attach	Solder	0.228614	Lead	7439-92-1	92.50	3.41	3.69
				Tin	7440-31-5	5.00	0.18	
				Silver	7440-22-4	2.50	0.09	
7	Die Coating	Silicone	0.125033	Polysiloxane	63148-62-9	22.11	0.45	2.02
				Chromium Sesquioxide	1308-38-9	5.67	0.11	
				Fumed Silica	112945-52-5	11.11	0.22	
				Filler	trade secret	61.11	1.23	
Total Weight			6.199631					